



Inventor: Kennedy et al.
Serial No.: 09/547,167
Attorney Dkt. No. 595.052-US1

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Art Unit: 2822
Examiner: C. Novacek

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T. BELL
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231

Inventor: **Kennedy et al.**

Serial No: **09/547,167**

Filed: **April 11, 2000**

For: **The Use of Sacrificial
Inorganic Dielectrics for
Dual Damascene Processes
Utilizing Organic Intermetal
Dielectrics**

Examiner: C. Novacek

Art Unit: 2822

Attorney Docket No.: 595.052-US1

RESPONSE TO OFFICE ACTION

The Honorable Commissioner
of Patents and Trademarks
Washington, D.C. 20231

Dear Sir:

This paper responds to the Office Action dated August 24, 2001. The three-month deadline, November 24th, falls on a Saturday; and therefore, this response is timely filed on Monday, November 26th, which is the next business day. Please enter the following:

IN THE CLAIMS (Clean Copy of Claims – Marked Up Copy Attached)

1. (Amended) A method of making conducting vias and conducting lines on a substrate comprising:
- depositing a stack having a top surface on a substrate, wherein the stack comprises a first organic intermetal dielectric layer and a hardmask layer;